TRIACs

February 2005

TOSHIBA CORPORATION
Semiconductor Company
Discrete Semiconductor Division

New TRIAC Line up

Main Characteristic				Sample Schedule	Mass-Pro Schedule	Packege Name	Schedule Product Name
IT(RMS)	VDRM	ITSM(A)	IGT (mA)				
2A	**400V**	12	10	ok	ok	TO-126	SM2G54
	800V						SM2L54
8A	**400V**	80	30	ok	ok	TO-220 SIS	SM8GZ52
	800V						SM8LZ52
10A	**400V**	100	30	ok	ok	TO-220 SIS	SM10GZ52
	800V						SM10LZ52
12A	**400V**	120	30	ok	ok	TO-220 SIS	SM12GZ52
	800V						SM12LZ52
16A	**400V**	160	30	Note1	Note1	TO-220 SIS	SM16GZ52
	800V						SM16LZ52

The maximum junction temperature of 150 degrees C is planned.

Note1: Please contact Tosdhiba

New Package : TO220SIS(Smart ISolation)

〈Feature〉

1) Lower Profile Package

To modified Stand off shape, 2.8 mm lower than currentTO-220NIS

2) Bonding Wire-less Assembly

Curtailment of the open fault by serge current

3) Lead free outer lead

100% lead free solder using for outer lead finish

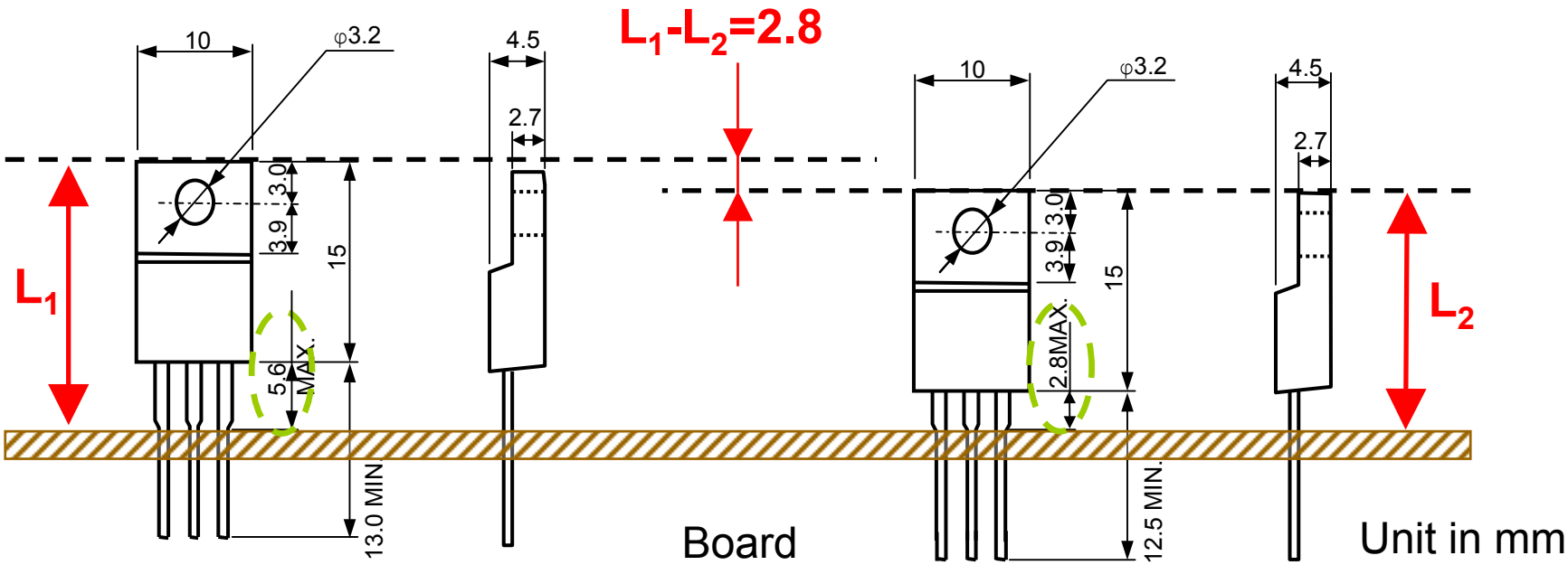
Mount Height : TO220NIS vs TO220SIS

Current Package:

TO-220NIS

New Package:

TO-220SIS



Lower Profile Package

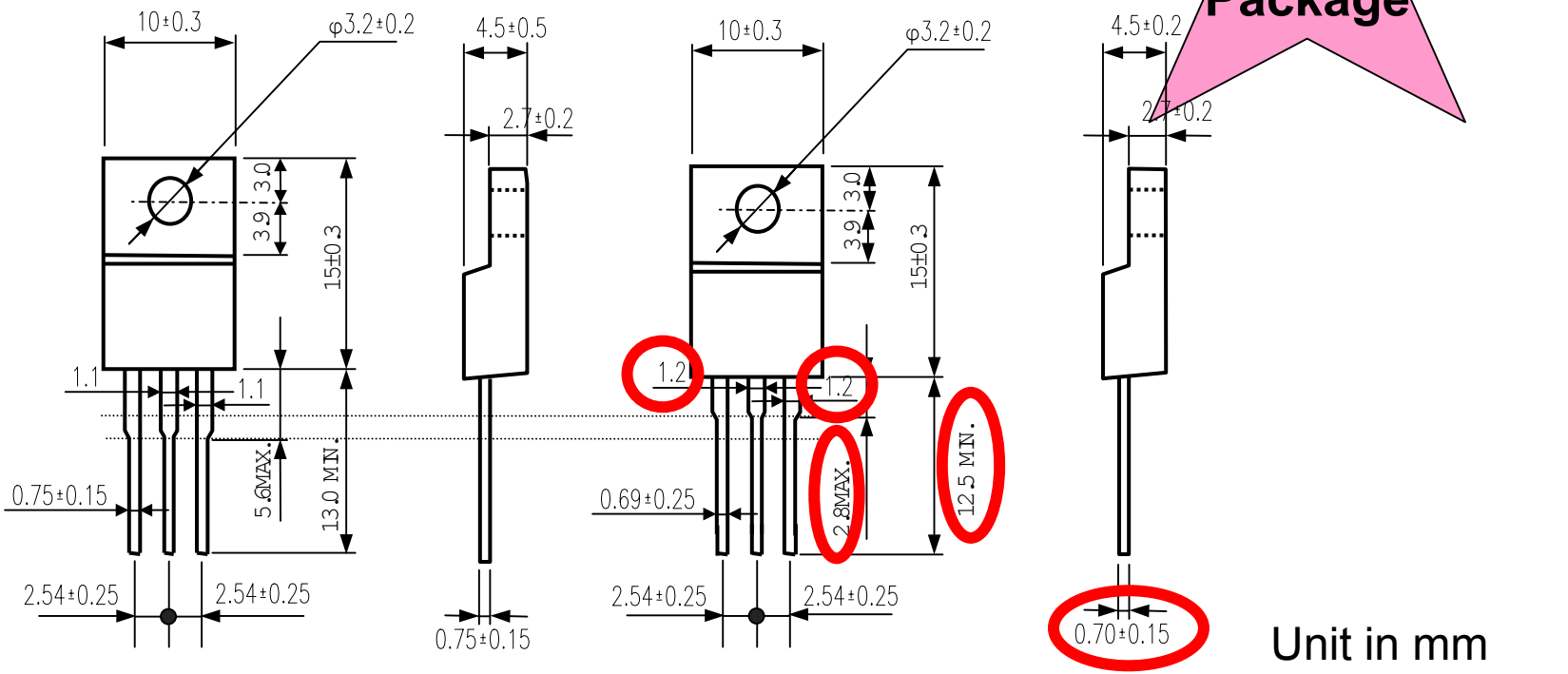
To modified Stand off shape, 2.8 mm lower than current TO-220NIS

Dimension: TO220NIS vs TO220SIS

TO-220NIS

TO-220SIS

New Package



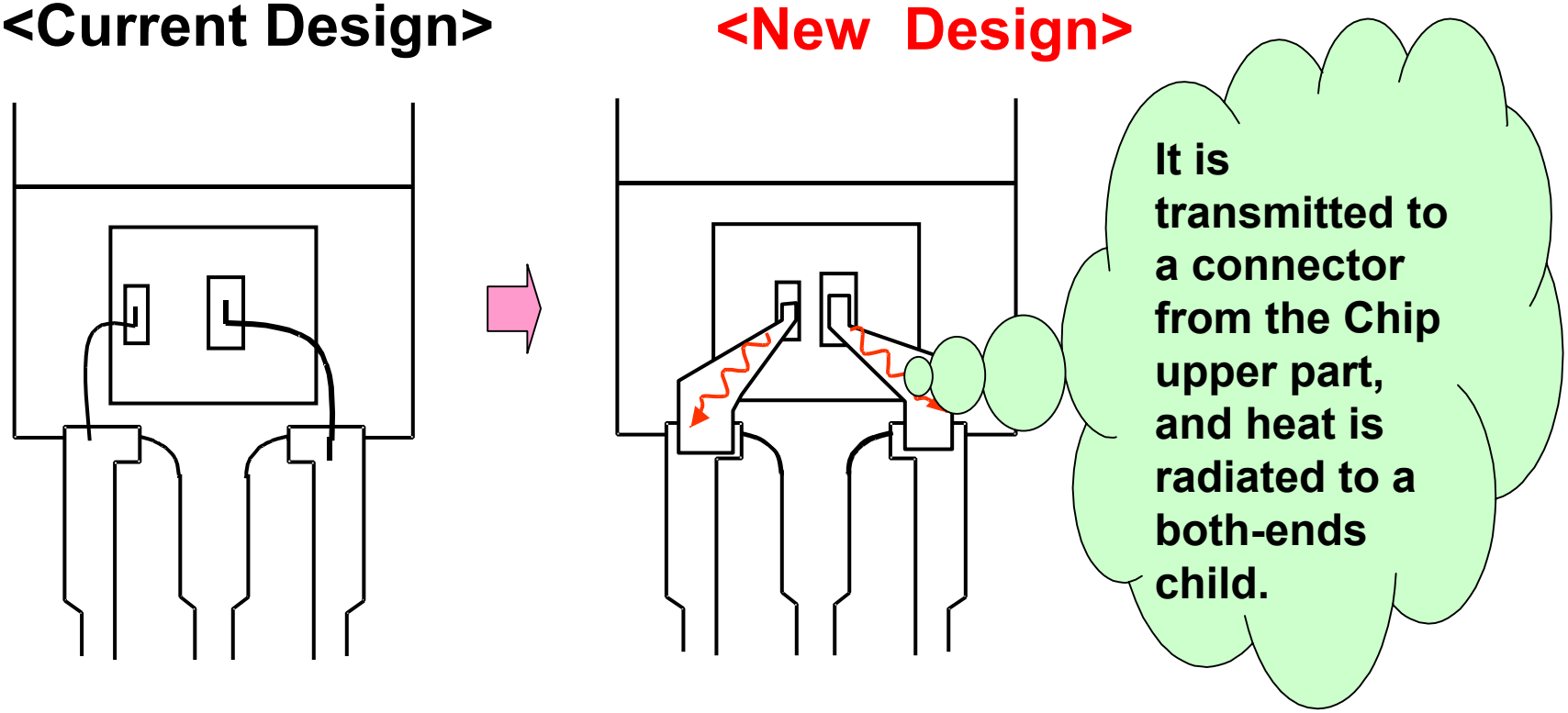
Unit in mm

TO-220SIS Series : Introduction of new technology

The heat dissipation efficiency rise by the formation of T1 terminal copper connector.

<Current Design>

<New Design>



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